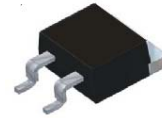


SMD
Power Thick film Resistors
Moulded, TO-263 Package

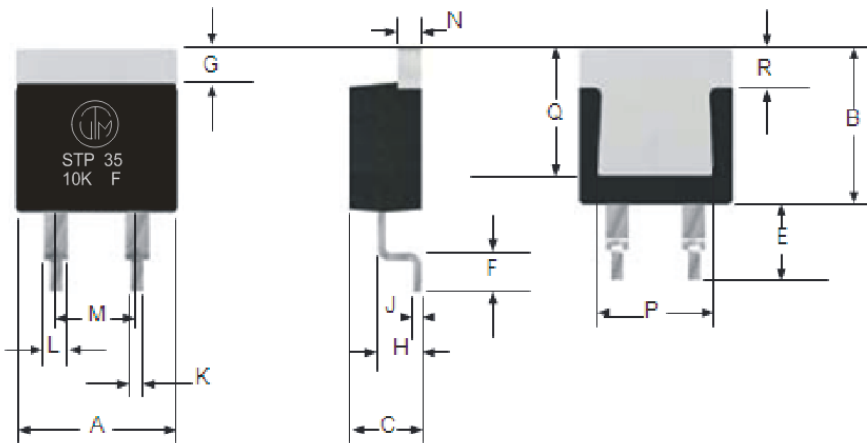
**ELECTRICAL SPECIFICATIONS**

Type		STP 35
Nominal Power rating P ₂₅	[W]	35
Resistance range	[Ω]	0R01 ... 550K
E-Series		E24
Tolerances	± [%]	1, 2, 5, 10
Temperature coefficient	[10 ⁻⁶ *K ⁻¹]	±250 (±150 upon request)
Temperature range	[°C]	-55 ... +175
Flammability IEC 60695-11-5	[s]	2 applications 30s separated by 60s

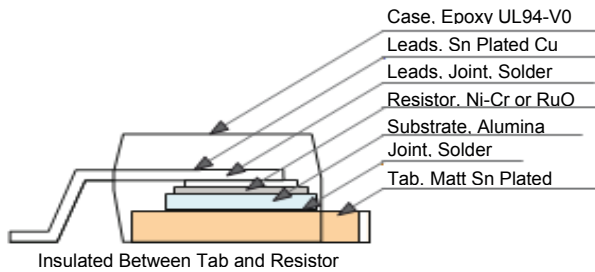
PERFORMANCE DATA

<u>Max. working voltage</u> IEC60115-1 clause 2.2.16	[V] _{RMS}	500
<u>Derating linear</u> IEC115-1 clause 2.2.24	[°C]	See next page
<u>Climatic category</u> IEC60068-1		55/175/56
<u>Endurance</u> IEC60115-1 clause 4.25 (P ₂₅ 25°C, 1000h)	± [%]	1
<u>Short Time Overload</u> (2x Rated power, not to exceed 1.5x rated voltage @ 5 sec. 25° [w]/ Heat Sink)	± [%]	0,25
<u>High Temperature Exposure</u> AEC-Q200 Rev C conditions: MIL-Std-202, method 108 (1000[h], +175 [°C], unpowered)	± [%]	0,25
<u>Temperature Cycling</u> IEC60068-2-14, JESTD020D	± [%]	0,5
<u>Moisture Resistance</u> AEC-Q200 Rev C MIL-Std-202	± [%]	0,5
<u>Biased Humidity</u> AEC-Q200 Rev C, MIL-Std-202, method 103 (1000h, 85 °C, 85% RH)	± [%]	1
<u>Vibration</u> AEC-Q200 Rev C conditions: MIL-Std-202, method 204 (5 g's for 20min., 12 cycles test from 10 Hz to 2000 Hz)	± [%]	0,5
<u>Mechanical Shock</u> AEC-Q200 Rev C conditions: MIL-Std-202, method 213 (100 g's, 6 ms, 3.75 m/s 3 shocks/direction)	± [%]	0,5
<u>Dielectric Withstanding Voltage</u> (Terminals to tab ; 60 sec, 1mA)	[V] _{AC}	2000
<u>Terminal strength</u> AEC-Q200 Rev C conditions: AEC-Q200-006 1.8kgf, 60 s	± [%]	0,25
<u>Resistance to soldering heat</u> IEC60115-1 ; IEC60068-2-58 (270°C, 10s)	± [%]	0,5
<u>Solderability</u> IEC 60068-2-20-T (230 ± 5°C, 3sec)	[s]	> 95% coverage
<u>Marking</u>		Printed in clear

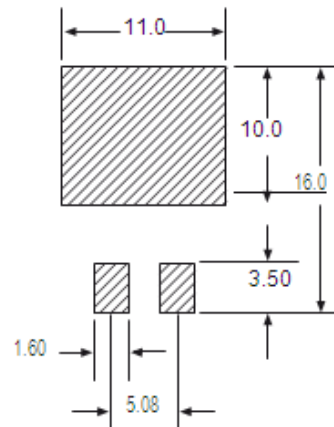
DIMENSIONS [mm]



A	10.1 ±0.2
B	10.3 ±0.2
C	4.5 ±0.2
E	5.0 ±1.0
F	2.5 ±0.5
G	2.2 ±0.2
H	2.75 ±0.2
J	0.5 ±0.05
K	0.75 ±0.05
L	1.5 ±0.05
M	5.08 ±0.1
N	1.5 ±0.05
P	7.4 ±0.1
Q	8.3 ±0.2
R	2.5 ±0.2

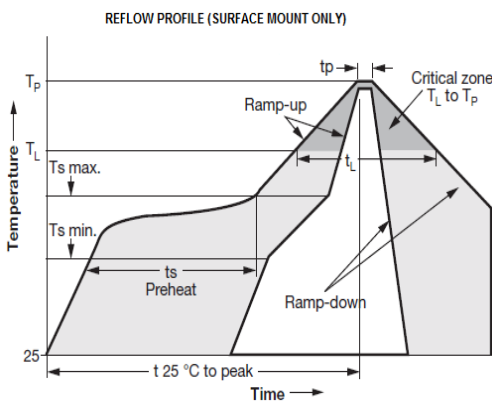


Footprint recommendation for solderable contact area



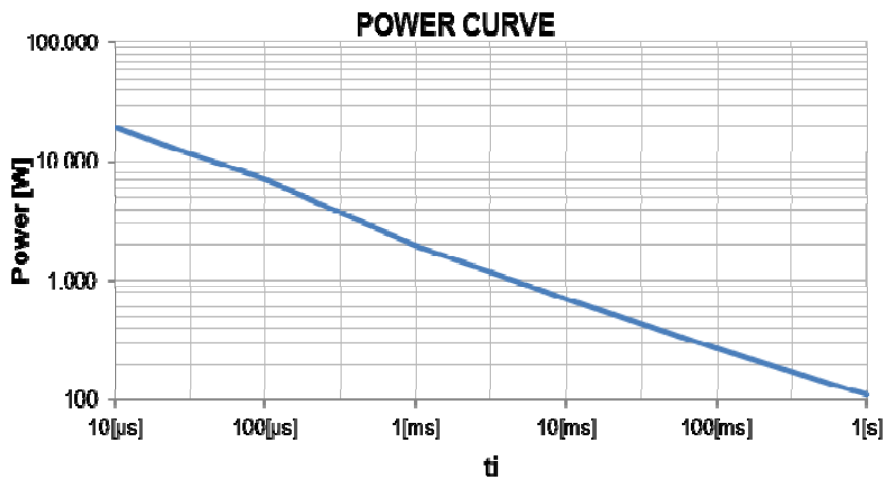
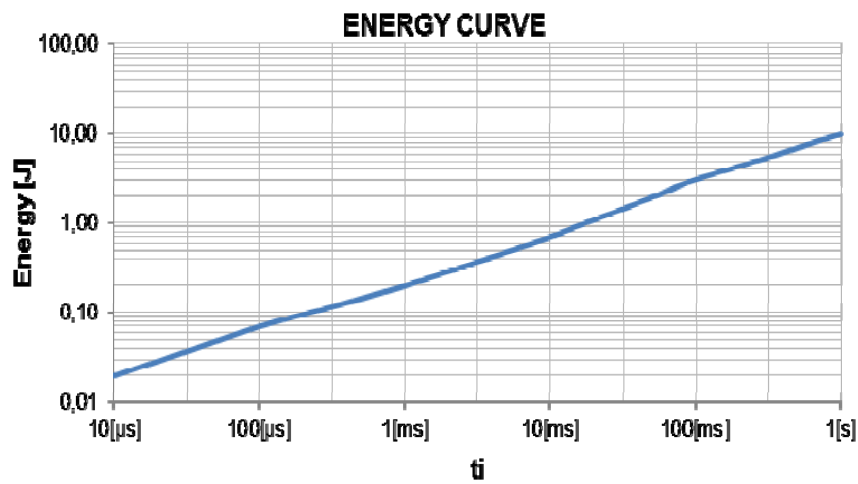
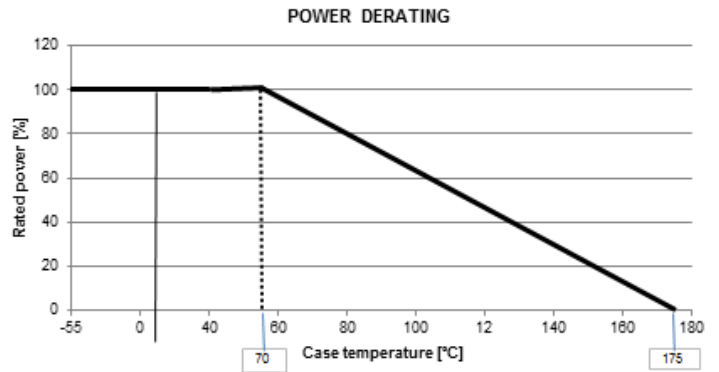
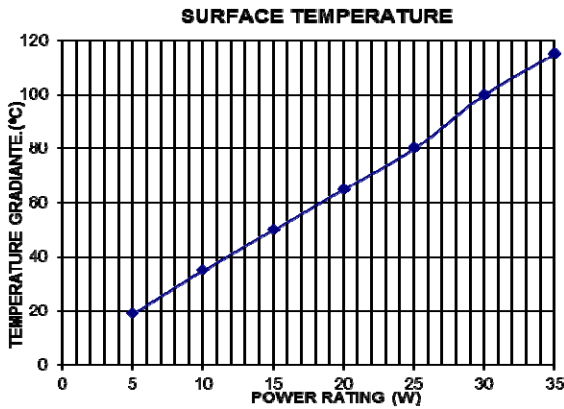
Lead & Tab Material	Tin Plated Copper
Part Weight	1.5g

SOLDER REFLOW PROFILE



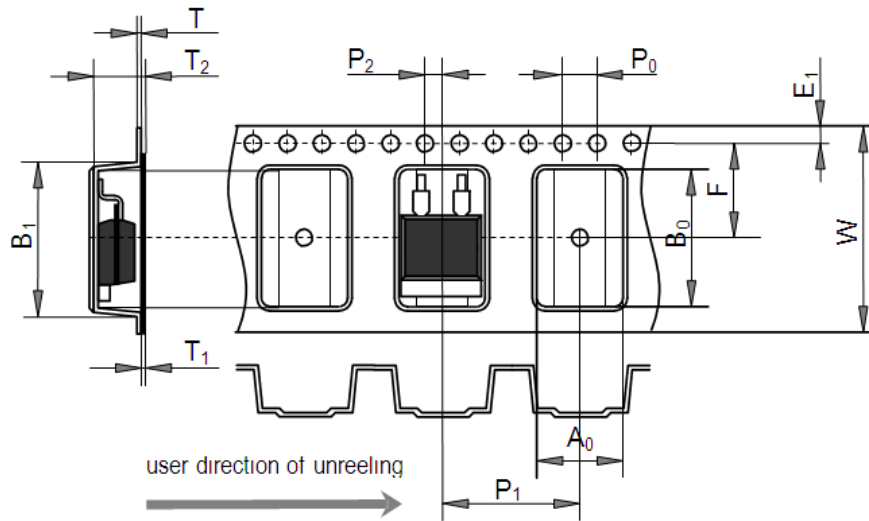
PROFILE	LEAD FREE
Preheat - Temperature minimum ($T_{S \text{ min}}$ [°C]) - Temperature maximum ($T_{S \text{ max}}$ [°C]) - Time (min. to max) T_S [s]	150 200 60 to 180
Time maintained above - Temperature (T_L [°C]) - Time (t_L [s])	270 60 to 150
Peak temperature	260
Time within 5 °C to actual peak temperature (t_p [s])	20 to 40
Ramp-down rate [°C/s]	6 (max)
Time 25 °C to peak temperature [min]	8 (max)

ELECTRICAL DATA



PACKAGING

Reel Packaging Data



Tape Dimensions [mm]												
Dim.	A ₀	B ₀	B ₁	E ₁	F	P ₀	P ₁	P ₂	T	T ₁	T ₂	W
Nom.	10.77	16.33	17.0	1.75	11.5	4.0	16.0	2.0	0.4	0.05	6.07	24.0
Tol.	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.05	----	0.1	+0.3/-0.1

Reel dimensions [mm]



Outer Diam.	330
Inner Diam.	100
Width	27.4 (max.)
Qty.	500 [pcs/reel]

ORDERING EXAMPLE

STP35	F	K	U	13	10K
Type	Tolerance	Blister tape reel	TC	reel diameter	R-Value
Tolerance		TC			
± 0,5 [%]	D	150 [10 ⁻⁶ *K ⁻¹]	T		
± 5 [%]	J	250 [10 ⁻⁶ *K ⁻¹]	U		
± 10 [%]	K				